

ABSTRACT

2 A method of radiantly marking substrates comprising
3 metals, plastics, ceramic materials, glazes, glass ceramics,
4 and glasses of any desired form, which comprises
5 electrostatically applying to the material to be marked a
6 variable thickness layer of marking material containing
7 energy absorbing components and/or enhancers, then
8 irradiating said layer with a radiant energy source such as
9 a laser or diode based energy source such that the radiation
10 is directed onto said layer, optionally in accordance with
11 the form of the marking to be applied, preferably using a
12 laser or diode based energy source of a wavelength which is
13 sufficiently absorbed by the marking material so as to
14 create a bonding of the marking material to the surface of
15 the workpiece at the irradiated areas.